

[UNDER BUMP METALLURGY LAYER]

Abstract

The present invention relates to an under bump metallurgy layer, comprising an adhesion layer, a barrier layer and a wetting- barrier layer. The adhesion layer, the barrier layer and the wetting- barrier layer are arranged sequentially on the pad of the chip, and the wetting- barrier layer is disposed between the barrier layer and the bump. The wetting- barrier layer, containing nickel, can improve the bonding ability between the pad and the bump. Also, the invention relates to a flip chip structure including at least a chip, a plurality of bumps and the under bump metallurgy mentioned above.